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Chen

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(54) **FUNCTIONAL FILM, ENVIRONMENTALLY SENSITIVE ELECTRONIC DEVICE PACKAGE, AND MANUFACTURING METHODS THEREOF**

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(58) **Field of Classification Search**
None
See application file for complete search history.

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(57) **ABSTRACT**

An environmentally sensitive electronic device package including a first adhesive, at least one first side wall barrier, a first substrate, and a second substrate is provided. The first adhesive has a first surface and a second surface opposite to the first surface. The first side wall barrier is distributed in the first adhesive. The first substrate is bonded with the first surface. The first substrate has an environmentally sensitive electronic device formed thereon and the environmentally sensitive electronic device is surrounded by the first side wall barrier. The second substrate is bonded with the second surface. A manufacturing method of the environmentally sensitive electronic device package is also provided.

13 Claims, 13 Drawing Sheets

